

-	1	wafer with LEAK	TEST	2003/03/18 11:41
-	2	wafer with LEAK	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:41
-	14	wafer with LEAK same pad	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:41
-	48	test0 same dram same wafer	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:43
-	5	test0 same dram same wafer same pad	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:43
-	7	test0 same dram same wafer and chain	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:43
-	4	test0 same dram and chain	EPC; JPC; DERWENT; IBM TDB	2003/03/18 11:43
-	487	test0 same dram and chain	USPAT; US-PGPUB	2003/03/18 11:44
-	100	test0 same dram and chain and wafer	USPAT; US-PGPUB	2003/03/18 11:44
-	48	test0 same dram and chain and daisy	USPAT; US-PGPUB	2003/03/18 11:44
-	14	(test0 same dram and chain) and daisy and wafer	USPAT; US-PGPUB	2003/03/18 11:44
-	14	(test0 same dram and chain) and wafer and daisy	USPAT; US-PGPUB	2003/03/18 11:44
-	143	wafer with dram and burn-in	USPAT; US-PGPUB	2003/03/18 12:20
-	116	(wafer with dram and burn-in) and pad	USPAT; US-PGPUB	2003/03/18 12:26
-	22	(wafer with dram and burn-in) and pad and test adj data	USPAT; US-PGPUB	2003/03/18 12:21
-	3	(wafer with dram and burn-in) and pad and daisy	USPAT; US-PGPUB	2003/03/18 12:26
-	15	(wafer with dram and burn-in) and pad and chain	USPAT; US-PGPUB	2003/03/18 12:27
-	6	(wafer with dram and burn-in) and pad and test adj data and chain	USPAT; US-PGPUB	2003/03/18 12:39
-	2	"0044944" or "0044944".PN.	USPAT; US-PGPUB	2003/03/18 12:40
-	3	"0411116" or "0411116".PN.	USPAT; US-PGPUB	2003/03/18 20:11
-	3	"0411116" or "0411116".PN.	USPAT; US-PGPUB	2003/03/18 21:18
-	1	"0044944".PN.	USPAT; US-PGPUB	2003/03/18 21:18